

MATERIAL DECLARATION SHEET



Material Number	SF-1206HHxxxM			
Product Line	Lead Free Multilayer High Current and High Inrush Chip Fuse			
Compliance Date	08/30/2017			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Body	Glass Ceramic	11.5212	Boron	7440-42-8	7.39%	6.0077%	81.297%
				Carbon	7440-44-0	2.11%	1.7153%	
				Aluminum	7429-90-5	18.65%	15.1615%	
				Silicon	7440-21-3	15.24%	12.3893%	
				Potassium	7440-09-7	0.53%	0.4309%	
				Oxygen	7782-44-7	56.08%	45.5902%	
2	Termination	Silver with Glass	1.5147	Silicon	7440-22-4	92.25%	9.8595%	10.688%
				Oxygen	7782-44-7	2.23%	0.2382%	
				Zinc	7440-66-6	1.64%	0.1757%	
				Silicon	7440-21-3	0.10%	0.0104%	
				Bismuth	7440-69-9	3.78%	0.4040%	
3	Fuse Link	Silver	0.4054	Silver	7440-22-4	100%	2.8609%	2.861%
4	Plating	Nickel	0.6376	Nickel	7440-02-0	100.00%	2.0203%	4.499%
		Tin		Tin	7440-31-5	100.00%	2.4788%	
5	Red Mark	Composite	0.0067	Oxygen	7782-44-7	50.86%	0.0250%	0.047%
				Aluminum	7429-90-5	16.02%	0.0079%	
				Silicon	7440-21-3	18.74%	0.0092%	

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				Potassium	7440-09-7	0.57%	0.0003%	
				Zinc	7440-66-6	9.82%	0.0048%	
				Iron	7439-89-6	3.99%	0.0020%	
6	Masking Layer	Glass Ceramic	0.0862	Boron	7440-42-8	9.83%	0.0598%	0.608%
				Carbon	7440-44-0	1.81%	0.0110%	
				Aluminum	7429-90-5	16.85%	0.1025%	
				Silicon	7440-21-3	15.58%	0.0948%	
				Potassium	7440-09-7	0.53%	0.0032%	
				Oxygen	7782-44-7	55.40%	0.3371%	
		Total weight	14.1718					

This Document was updated on: 8-30-2017

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.